

Title (en)

POWER MODULE, POWER CONVERTER AND DRIVE ARRANGEMENT WITH A POWER MODULE

Title (de)

LEISTUNGSMODUL, STROMRICHTER UND ANTRIEBSANORDNUNG MIT EINEM LEISTUNGSMODUL

Title (fr)

MODULE DE PUISSANCE, CONVERTISSEUR ET ENSEMBLE D'ENTRAÎNEMENT POURVU D'UN MODULE DE PUISSANCE

Publication

EP 2989868 A1 20160302 (DE)

Application

EP 14722569 A 20140417

Priority

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- EP 2014057875 W 20140417

Abstract (en)

[origin: WO2014173801A1] A power module (LM) is disclosed for a power converter (SR), which power module (LM) has: – a first busbar (SS1) with a first surface (O31) and a second surface (O 32) lying opposite the first surface (O31), – a first semiconductor component (H1) on the first surface (O31) of the first busbar (SS1), which semiconductor component (H1) has a first surface (O11) with a first electrical surface contact connection (K11) and is connected, via the first surface contact connection (K11), to the first surface (O31) of the first busbar (SS1) in an electrically conductive and mechanical fashion over an area, and – a second semiconductor component (H2) on the second surface (O32) of the first busbar (SS1), which semiconductor component (H2) has a first surface (O21) with a first electrical surface contact connection (K21) and is connected, via the first surface contact connection (K21) of the second semiconductor component (H2), to the second surface (O32) of the first busbar (SS1) in an electrically conductive and mechanical fashion over an area.

IPC 8 full level

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CPC (source: EP US)

H01L 23/49537 (2013.01 - EP US); **H01L 23/49548** (2013.01 - EP US); **H01L 23/49562** (2013.01 - EP US); **H01L 23/49568** (2013.01 - EP US); **H01L 23/49575** (2013.01 - EP US); **H02B 1/20** (2013.01 - US); **H02M 1/08** (2013.01 - US); **H05K 7/1432** (2013.01 - US); **H05K 7/14329** (2022.08 - EP); **H01L 24/06** (2013.01 - EP US); **H01L 24/29** (2013.01 - EP US); **H01L 24/32** (2013.01 - EP US); **H01L 24/33** (2013.01 - EP US); **H01L 2224/04026** (2013.01 - EP US); **H01L 2224/06181** (2013.01 - EP US); **H01L 2224/291** (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/33181** (2013.01 - EP US); **H01L 2924/1203** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/1306** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US)

Citation (search report)

See references of WO 2014173801A1

Designated contracting state (EPC)

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